



Accelerate development time through reuse of flight-proven designs with new gen R9 rad hard Si MOSFETs

Andrew Popp, Andrew.Popp@infineon.com
Presented at Space Power Workshop 2021

Speaker introduction

- › Andrew Popp is Director of Discrete Space Power Products for IR HiRel, an Infineon Technologies company
- › Andrew leads IR HiRel's development of new silicon and GaN-based FET solutions for the Space Industry



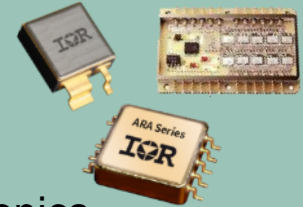
Agenda

- 1 High reliability electronics for space
- 2 Project motivation
- 3 Converter design
- 4 Measurements and performance
- 5 Power conversion efficiency

About IR HiRel

What we do

- Radiation-hardened semiconductor-based power conversion for high-reliability applications in space and other extreme environments
 - Rad hard MOSFETs
 - DC-DC hybrid converters
 - Custom PWB-based power supplies
 - Ruggedized industrial modules
- Specialized expertise in radiation-hardened power electronics
- Broad selection of solutions certified to industry standards for global customers



Why customers trust IR HiRel

- World-class space heritage, flight-proven globally in thousands of programs
- Demonstrated track record of high-reliability products, portfolio longevity and long-term customer commitment
- Flexible model to tailor solutions to specific customer needs
- Minimizing risk with fully qualified, documented products to expedite approvals

Committed to our markets

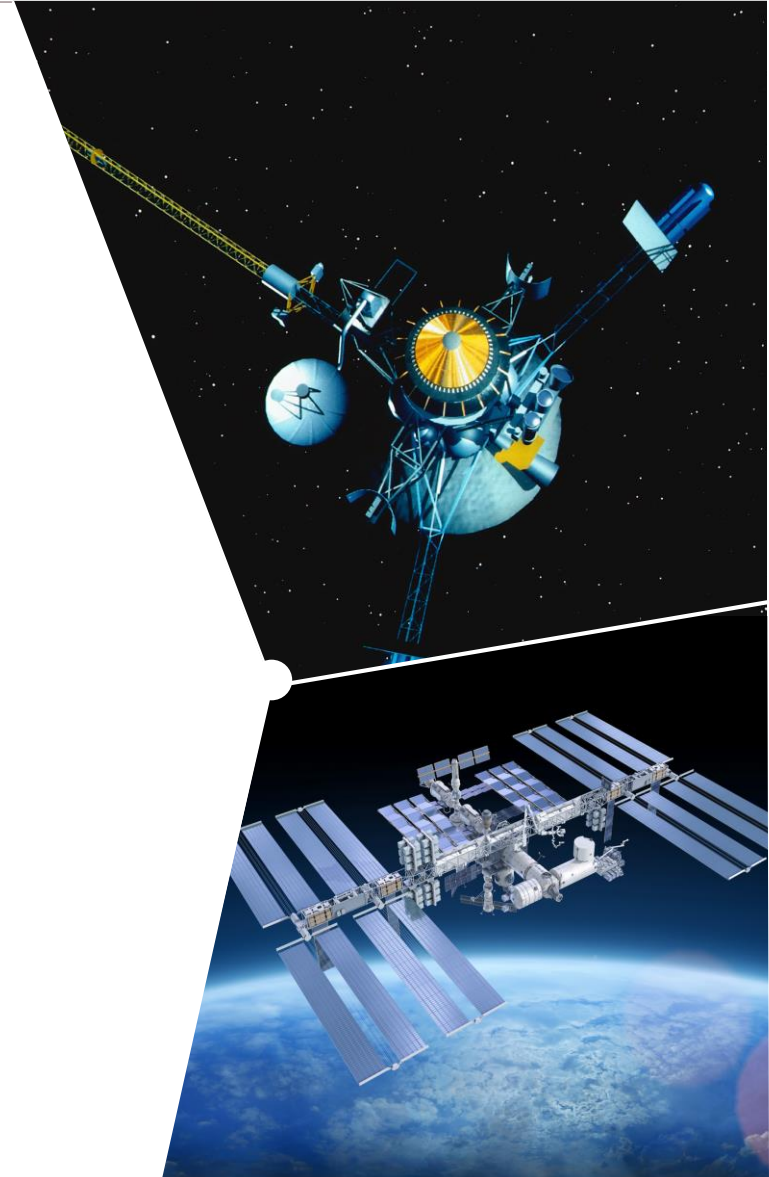
- Global access to dedicated customer support team, including sales, applications support, quality and customer service
- Certification to industry standards, including MIL-PRF-38534, MIL-PRF-19500



Failure-free performance for space applications

- › Power electronics in highly reliable space vehicles must survive and perform to specification in the harshest environments
 - Severe thermal, mechanical and radiation conditions
 - Mission lifetimes 15 years+
 - Especially important for high cost, limited redundancy satellites and vehicles

- › To improve system efficiency, IR HiRel continuously develops newer radiation hardened (rad hard) MOSFETs with enhanced performance and packaging



Project motivation: improve system performance and efficiency with minimal circuit component changes

> Unique challenges in high reliability applications

- Balance resources spent to optimize gate-driver circuit and board layout
- Expedite time to deploy electrical power system for newer projects
- Improve system performance with minimal circuit component changes

> DC-DC converter base hardware

- Existing printed wiring board (PWB) layout
 - 190W output power
 - Flight-proven design
 - Used IR HiRel's R5 Si MOSFETs

> Design goals

- Use same converter topology and control strategy
- Replace R5 with R9 Si MOSFETs
- Minimal changes to other circuit components



Demonstrate competitive peak performance in heritage isolated DC-DC converter

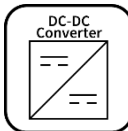
> 260W rad hard DC-DC converter

- Full-bridge with current doubler synchronous rectifier
- Single 24V output voltage with peak current mode for closed-loop control
- Power stage with IR HiRel's latest generation rad hard R9 MOSFETs in SMD-0.5e package



Parameters	Conditions	Min	Max	Unit
Input voltage	Steady-state	48	52	V
Output voltage	Steady-state	24V ± 0.01V		V
Output current	Steady-state	0	11	A
Switching frequency	Steady-state	120		kHz
Power efficiency	Load: 37% to 100% Temperature: -45°C to +85°C	93	95.5	%

Table 1. Key DC-DC converter specifications



Maximize design reuse and improve performance

- > Main driving factors for topology selection
 - Galvanic isolation
 - Higher power conversion efficiency
 - Improved thermal performance

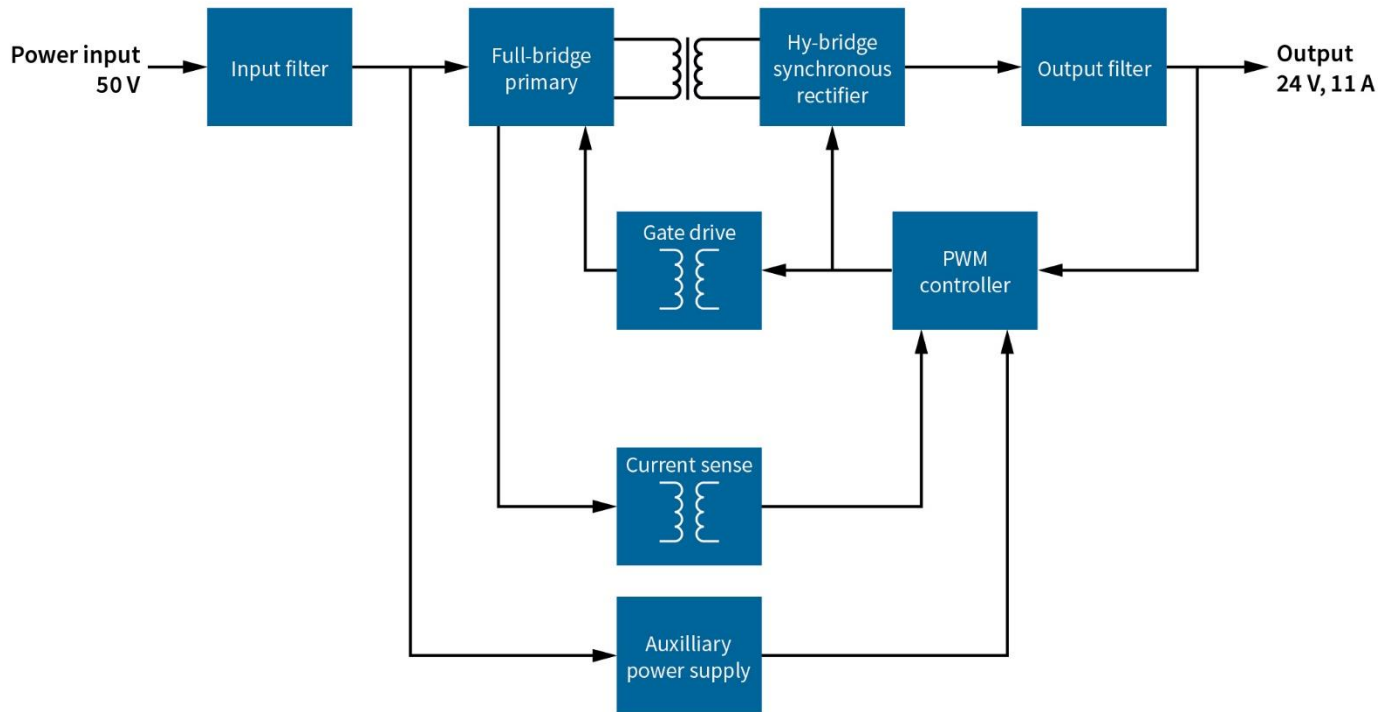


Figure 1. Block schematic of IR HiRel's rad hard 260W isolated DC-DC converter



Power stage topology improves thermal performance

- › Current doubler output stage efficiently provides high-current output
 - Each inductor has to handle only half of output current (plus switching current ripple)
 - Reduces the height profile, saves board space
- › Compared to center-tapped transformer in output stage, current doubler stage transformer is fully utilized and has lower leakage inductance
- › The design specifications are standard and have been used for various space applications

100V, 35A rad hard R9 MOSFET (IRHNKC9A7130)	
Low $R_{DS(on)}$	34 m Ω
Gate charge	48 nC at room temp
TID	100krad
SEE	Up to 90 MeV/mg/cm ² LET

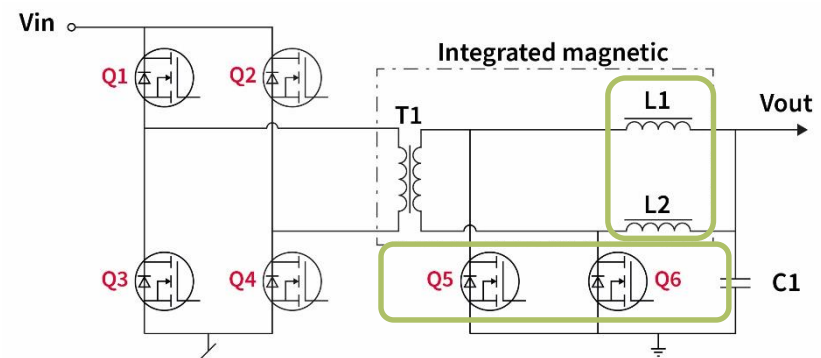


Figure 2. Power stage schematic (simplified)

Minimize transients with peak current mode control

> Control stage

- Current mode control used to ensure that current through both inductors is the same
- Closed-loop control
 - UC1825 rad hard controller IC
 - Peak current mode with slope compensation
 - Limits duty-cycle for each PWM output
- Current through the switches is measured using current sense transformer
- PWM signals are generated by gate drive transformer

> EMI filter

- Input filter uses 2nd order LC filter with LR dampening
- The selected topology means that EMI 1st harmonic for both input and output is twice the switching frequency

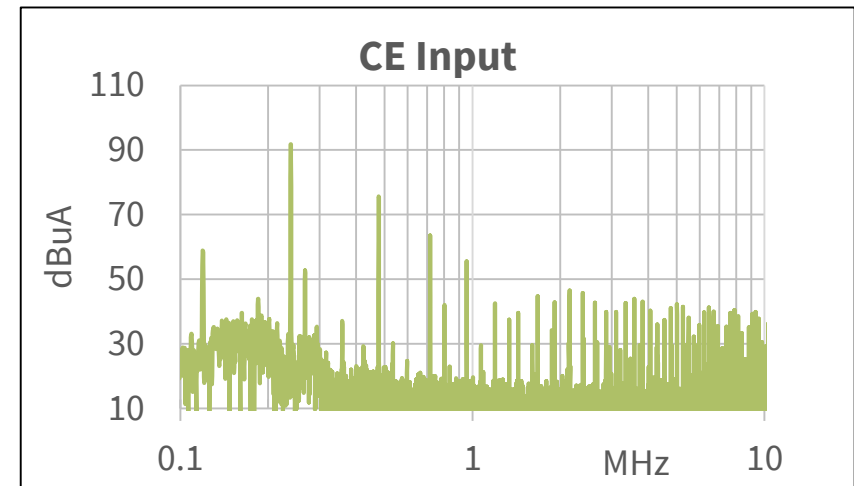


Figure 3. Conducted EMI at input of DC-DC converter

Stable and nominal waveforms

- > Amobeads are used in series with drain of MOSFETs to reduce the overshoot in drain-source voltage
- > Converter efficiency can be improved by optimizing/reducing amobead size, but at the expense of voltage overshoot
- > For low-side switch in full-bridge primary, a nominal voltage (during off-state) of 50V is noted (Ch2)

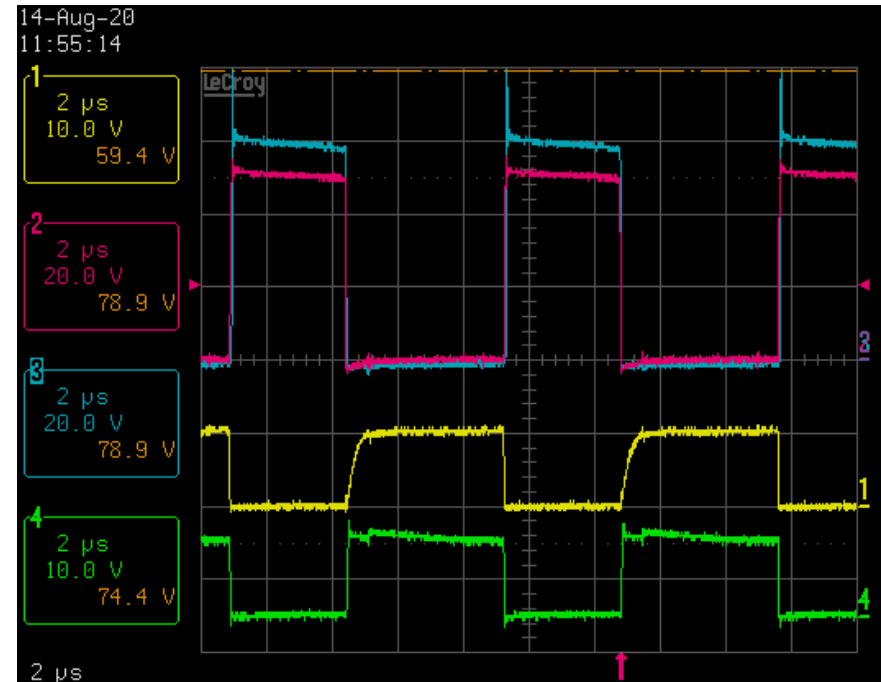


Figure 4. Gate and drain voltage waveforms across MOSFETs Q4, Q6

- Ch1 – Gate voltage (Q4) – Low-side switch in full-bridge
- Ch2 – Drain voltage (Q4) – Low-side switch in full-bridge
- Ch3 – Drain voltage (Q6) – Low-side switch in synchronous rectifier
- Ch4 – Gate voltage (Q6) – Low-side switch in synchronous rectifier

Minimize output voltage ripple

- > With two output inductors operating in parallel and 180° phase shifted
 - Output ripple frequency is 2x the switching frequency
 - Output ripple current through capacitor is reduced
 - Output ripple voltage is reduced
 - Reduces the size of output capacitor required

- > For an output of 24V, peak-to-peak voltage ripple of 25.7mV (1.46mV rms) is observed

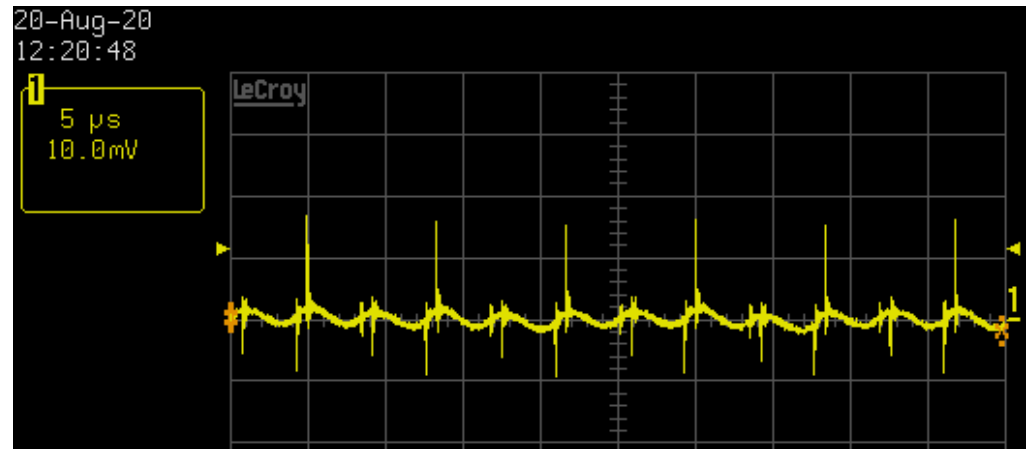


Figure 5. Output voltage ripple*

**The asymmetry observed in the waveform of output voltage ripple is due to the noise from the main transformer being picked up by the measuring probe at output.*

Power conversion efficiency

based on parameter values at room temperature

Rad hard MOSFET generation	Max load	Operating efficiency
R9	260W	95.49%
R5	195W	94.89%
R9	195W	95.89%

*modeled calculations

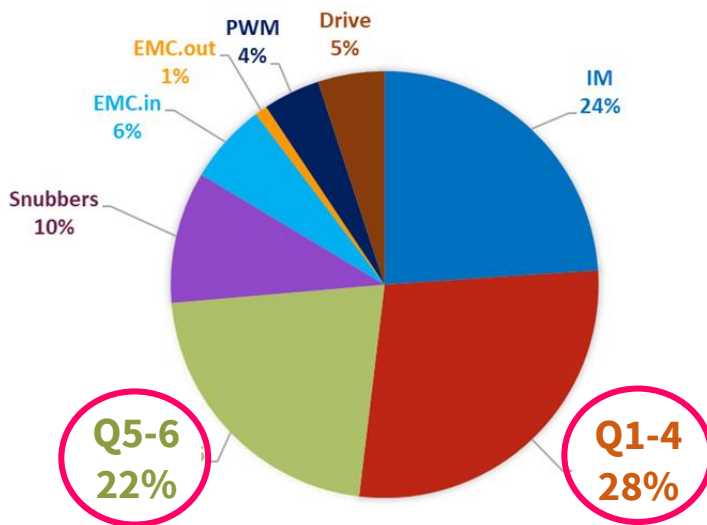


Figure 6. Power losses distribution in 195W DC-DC converter with **R9 MOSFET (IRHNKC9A7130)**

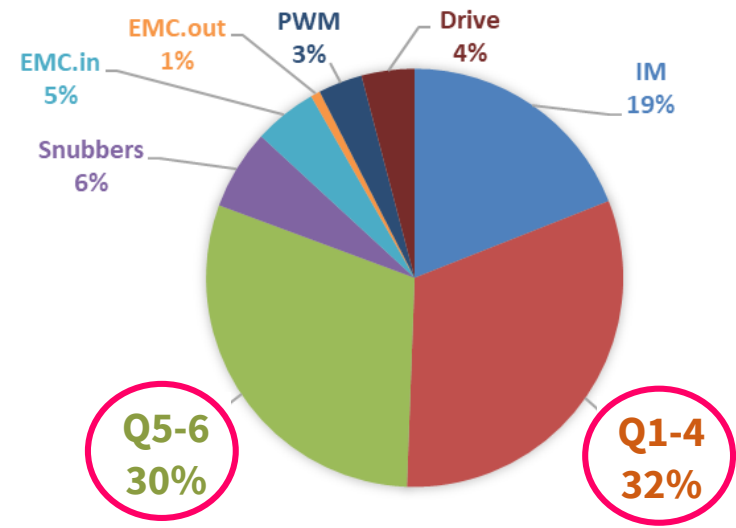


Figure 7. Power losses distribution in 195W DC-DC converter using **R5 MOSFET (IRHNJ57130)**

Power conversion efficiency

comparing R9-based DC-DC converter to prior MOSFET generations

- › **R9 MOSFET delivers the highest efficiency and greatest output power**
- › Each newer generation Si MOSFET shows
 - improved efficiency
 - higher load capability
- › Circuit reuse enables faster system design and approvals while delivering improved performance and reliability

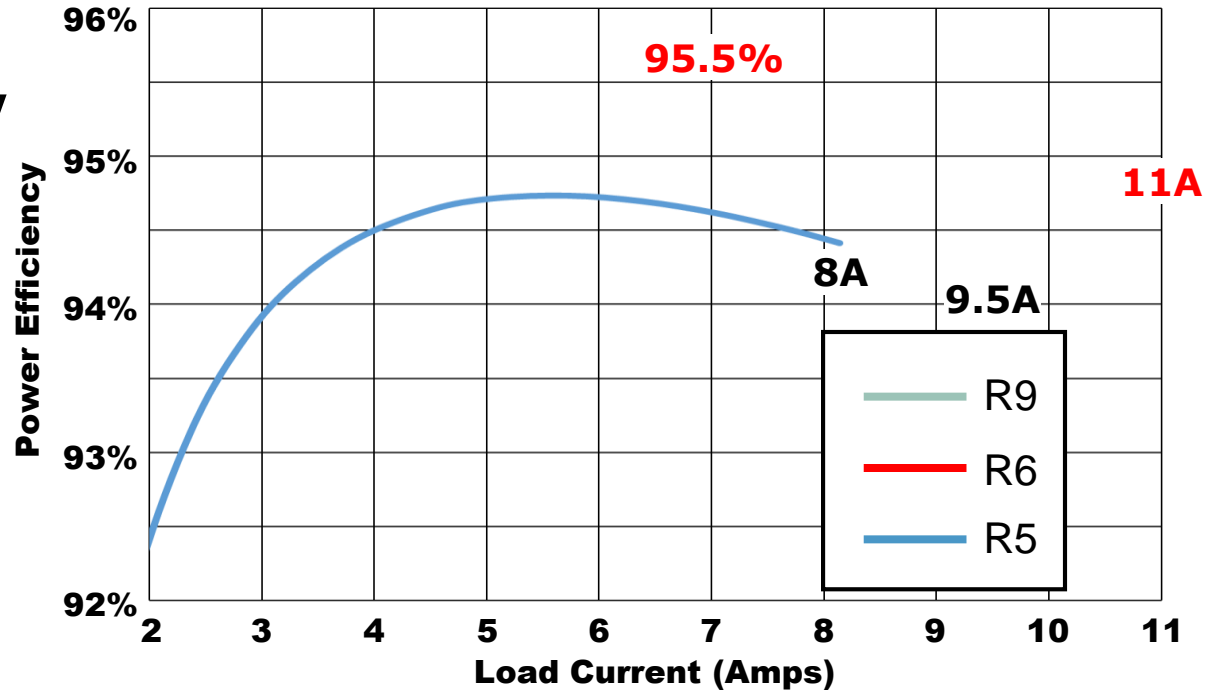


Figure 8. Modeled efficiency vs. load curve of rad hard DC-DC converter at 25°C baseplate temperature ($V_{out} = 24V$)

Peak efficiency of 95% is observed at 22°C

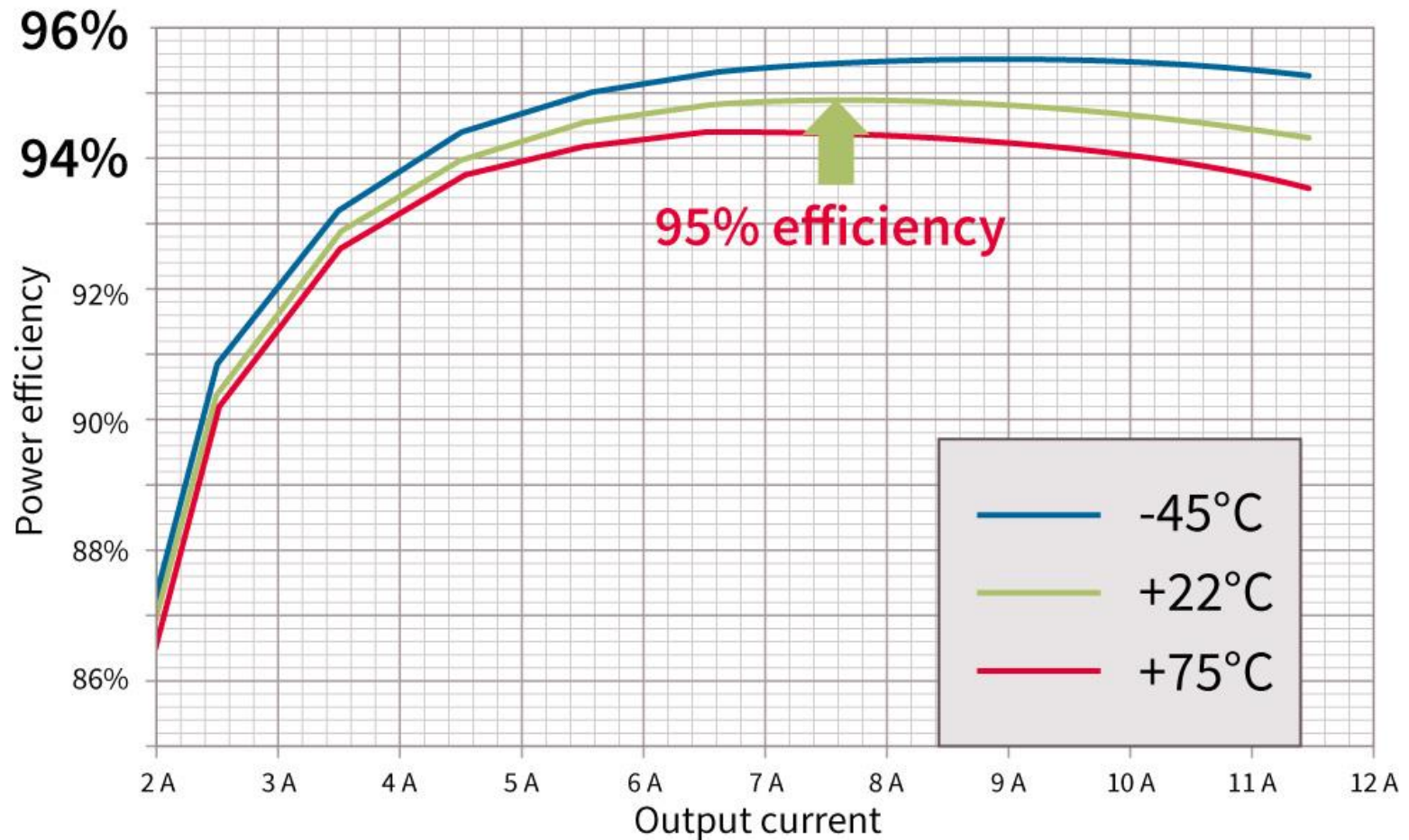
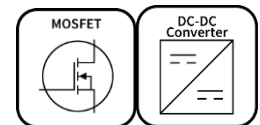


Figure 9. Measured efficiency vs. load curve
(without auxiliary power supply consumption)

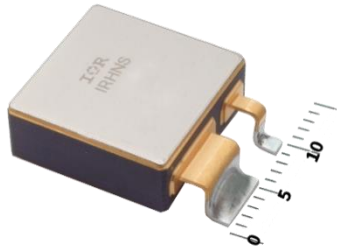
R9 rad hard Si MOSFETs enable higher efficiency and power density in flight-proven designs

- › This 260W DC-DC converter shows a best-in-class peak power conversion efficiency of 94.55% at room temperature
- › Reuse heritage DC-DC converter designs easily with R9 Si MOSFETs
 - Improved power efficiency
 - Higher output power
 - Simple drop-in MOSFET replacement
 - Minimal circuitry changes
 - Low-risk upgrade path for immediate benefits

IR HiRel
R9 MOSFETs
Improve circuit performance
N-channel and P-channel



Portfolio innovations enable higher performance, greater power densities and design reuse



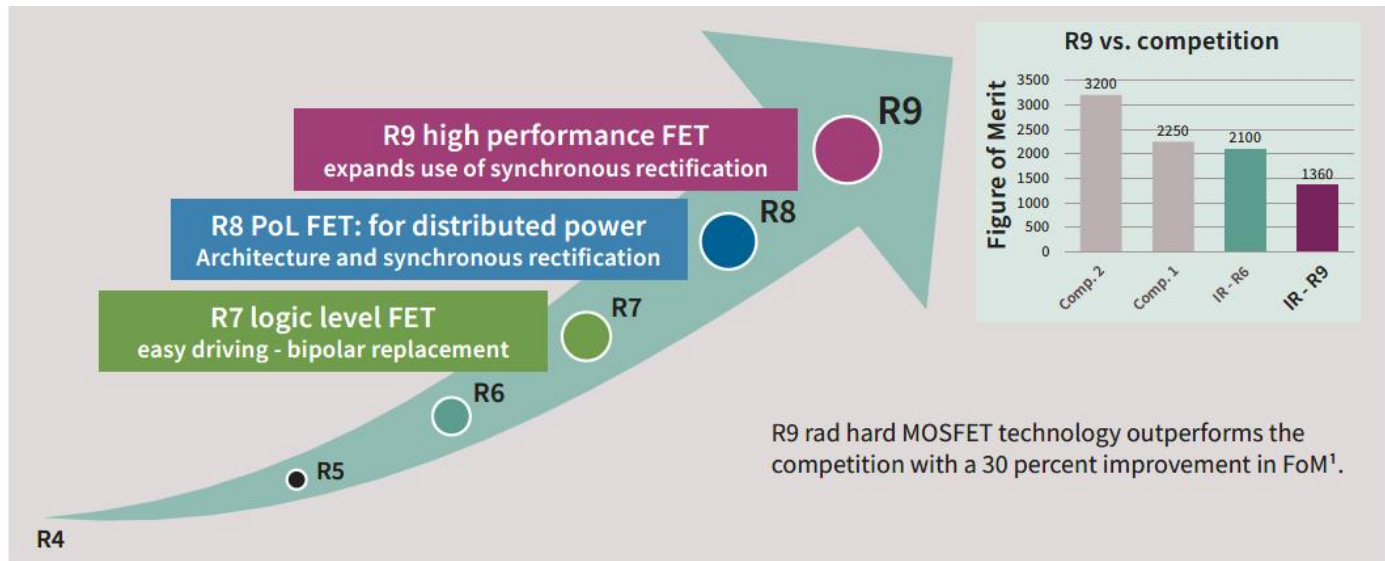
SupIR-SMD

Better than SMD-2 on Carrier, 37% smaller and 45% lighter

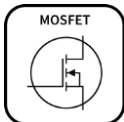


SMD-0.5e

Improved design
Direct-to-PCB mounting



¹ Figure of Merit is $R_{DS(on)} \times Q_G$ (Gate Charge)



R9 offers designers more choices

R9 vs R5 N-channel

- > Same electrical performance, smaller package size (SMD-0.2 v SMD-0.5)
- > Same package size, better performance (FoM 0.81 v 1.35)
- > Reduced BoM by using higher voltage device for lower voltage socket (100V v 60V)

	R9	R5	R9	R9
Voltage	60V		100V	
FoM	0.93	1.35	0.81	1.63
Id (A)	25	22	40	35
Package	SMD-0.2	SMD-0.5		
	IRHNMC9A7024	IRHNJC57034	IRHNJC9A7034	IRHNJC9A7130

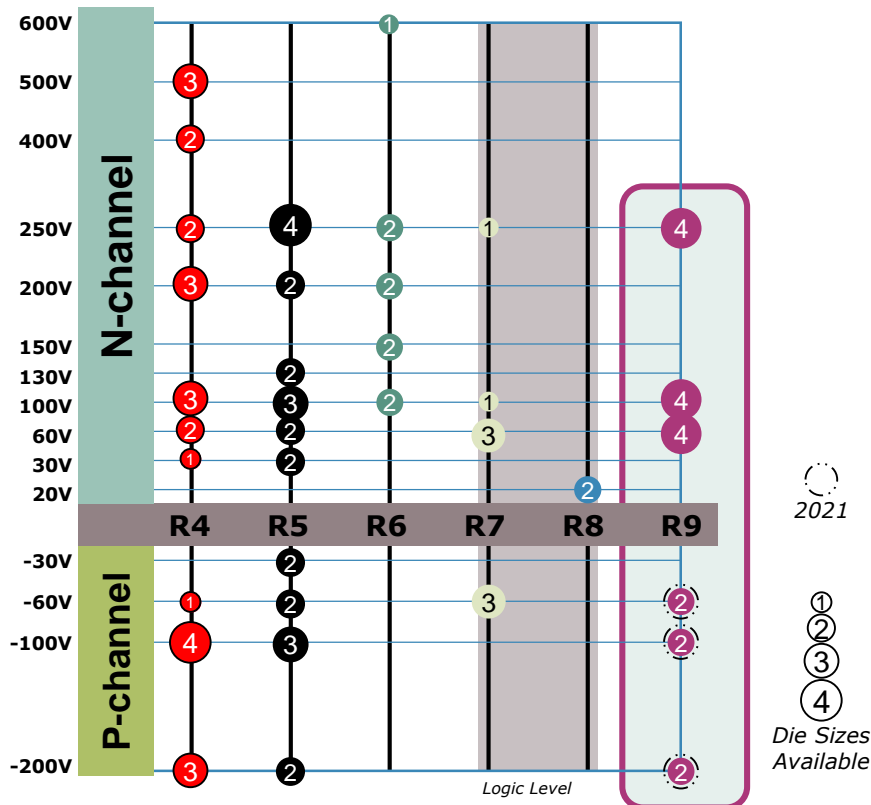
R9 offers designers more choices

R9 vs R5 vs R6 N-channel

- > 100V requirements
 - R9 has improved FoM even with a smaller package
 - R9 can be used at higher current in the same package

	R9	R5	R6	R9
Voltage	100V			
FoM	1.26	3.0	2.1	1.63
Id (A)	23	22	22	35
Package	SMD-0.2	SMD-0.5		
	IRHNMC9A7120	IRHNJC57130	IRHNJC67130	IRHNJC9A7130

Industry-leading rad hard MOSFET product portfolio, most are available as DLA-qualified QPLs

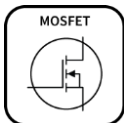


N-channel: 20V to 600V

P-channel: -30V to -200V

- **R9** Best all-around Figure of Merit
- **R8** Designed for low voltage POL designs
- **R7** Designed for logic level gate drives
- **R6** Best performance for mid to high-voltage designs
- **R5** Optimized performance for low to mid-voltage designs
- **R4** All purpose MOSFET, legacy design with extensive space heritage

IR HiRel performs 100% screening of all components in accordance with specified quality levels, including MIL-PRF-19500 and MIL-STD-750





Andrew Popp, Andrew.Popp@infineon.com
Director Discrete Space Products

IOR HiRel
An Infineon Technologies Company